

C1206X331FBGACTU

Aliases (C1206X331FBGAC7800)

SMD Comm COG HV Flex, Ceramic, 330 pF, 1%, 630 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1206



Click [here](#) for the 3D model.

Dimensions

Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	1mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	false
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms